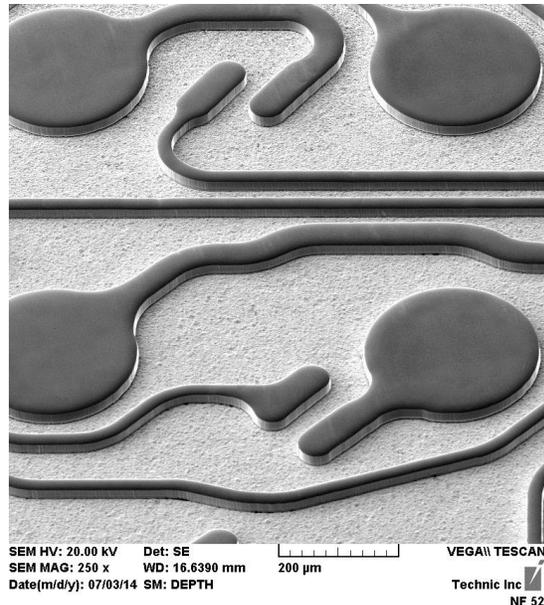
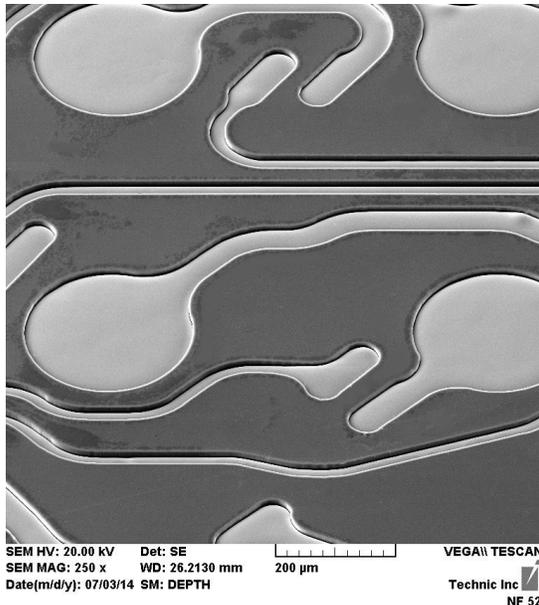


*For immediate release*

## Technic Announces the Release of **TechniStrip NF52** Full Dissolution Photoresist Remover for Advanced Packaging Applications



Technic has announced the release of **TechniStrip NF52**, a photoresist stripper for TSV, copper pillar and other advanced packaging applications. **TechniStrip NF52** operates as a negative tone photoresist remover, specifically formulated for use with laminated and liquid photoresist.

**TechniStrip NF52** provides full dissolution of most photoresist without the use of harmful products such as NMP and Hydroxylamine. **TechniStrip NF52** successfully performs without any negative impact to the copper surface, preserving critical fine features that would otherwise be negatively impacted by photoresist strippers that can etch into fine surface details.

“For several of today’s advanced packaging structures, lift-off of the resist is no longer acceptable. Only strippers that provide full dissolution while preserving fine surface details can meet the demands of today’s advanced packaging customers. **TechniStrip NF52** is a highly effective photoresist remover while being compatible with numerous substrates.”

- Anthony J. Gallegos  
Global Product Manager, Semiconductor Technology

**TechniStrip NF52** has been documented to perform with an extended bath life that is typically 2 – 3 times greater than standard photoresist strippers, resulting in a significant decrease of operational costs.

For information on Technic and Technic products go to: [www.technic.com](http://www.technic.com) or call us at (401) 781-6100.

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